

ORDER INFORMATION:

MATERIAL


Insulator : LCP+30% G.F. , UL 94V - 0 rated. Color Black.
 Contact : Phosphor Bronze

PLATING

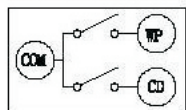
Contact Area:Hard gold plating over 1.27 um(50u") min Nickel underplating.
 Soldering Zone:3.05um(120u")min. 100% Tin, or Lead-free plating per
 part number designation, over Nickel underplating.
 Unerplating: 1.27 um(50u")min. Nickel allover.

$$SD - P2 - \frac{X}{a} \frac{X}{b}$$

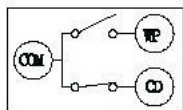
- a. Stand off options :
 - 0 : stand off = 0.0mm
 - 2 : stand off = 1.5mm
 - 3 : stand off = 1.8mm
 - 4 : stand off = 2.0mm
- b. Au contact area/solder in soldering zone:
 - E : 5u" Au/120u" Tin,100%
 - F : 10u" Au/120u" Tin,100%
 - G: 15u" Au/120u" Tin 100%

GENAL TOLERANCE X. ± 0.3 .X ± 0.2 .XX ± 0.1 .XXX ± 0.05	DRAW 2006/04/14 DATE H. D. LI	PART NO SD - P2 - XX
	DESIGN H. D. LI	TITLE SD PUSH-PUSH Assembly (I/O)
	CHECKED Y. M. LU	
UNIT :mm	APPROVED J. F. KANG	 宏揚精密有限公司 HOJAR PRECISION CO., LTD.

CIRCUIT without CARD

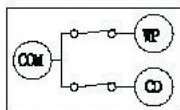


CARD INSERTED



● Write Protect SW. : Lock
● Status: Read only

CARD INSERTED



● Write Protect SW. : Unlock
● Status: Write enable

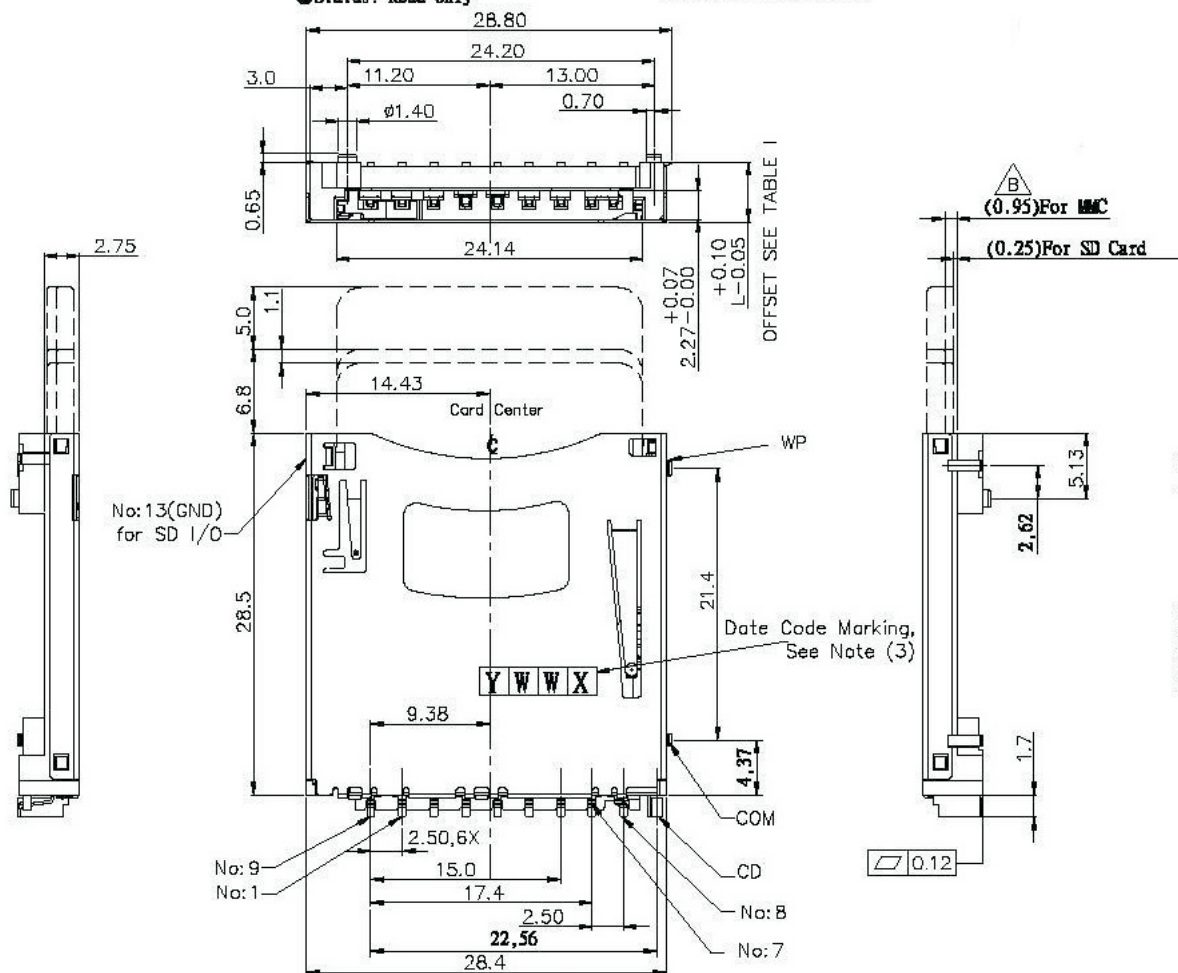
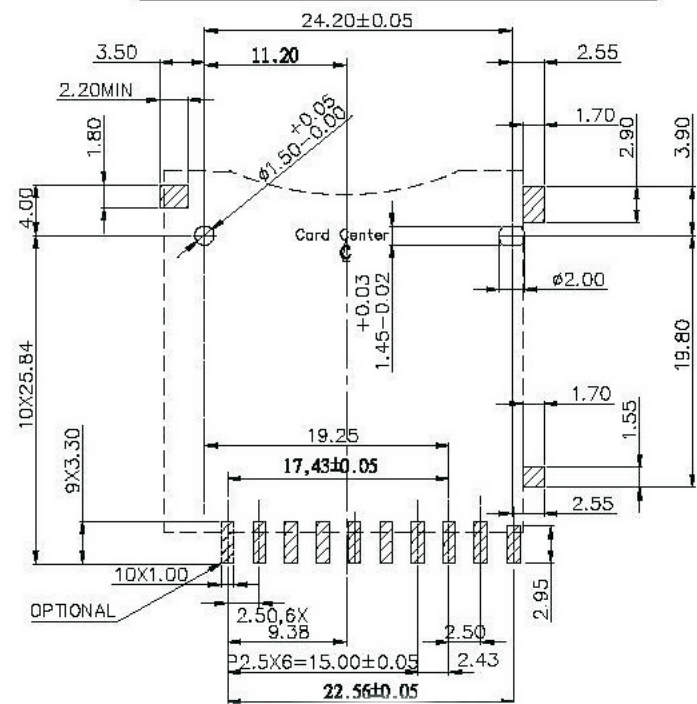



Table 1

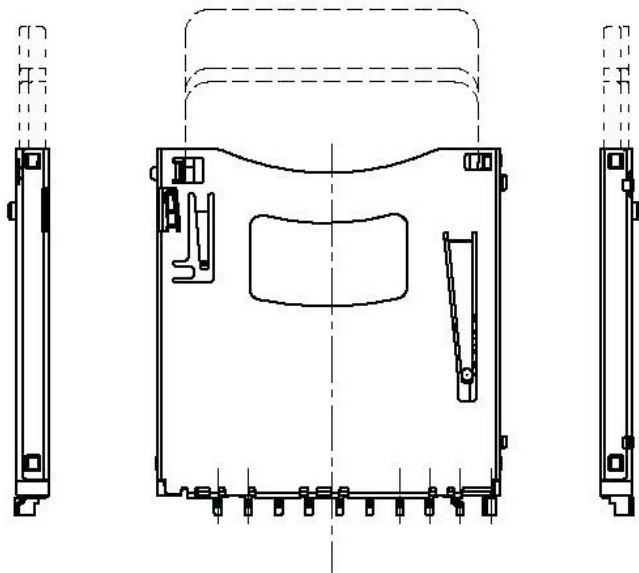
Part NO	Standoff	"L"
SD-P2-0X	0.0mm	2.75mm
SD-P2-2X	1.5mm	4.25mm
SD-P2-3X	1.8mm	4.55mm
SD-P2-4X	2.0mm	4.75mm

Recommended P.C.Board Layout-STYLE 1

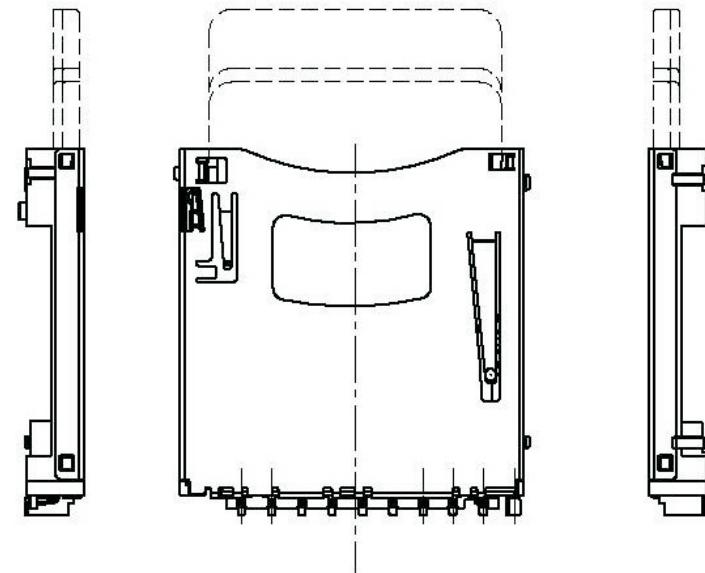



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UNIT :mm		 宏揚精密有限公司 HOJAR PRECISION CO., LTD.

Standoff 0.0mm



Standoff 1.5mm, 1.8mm ,2.0mm



GENAL TOLERANCE X. ± 0.3 .X ± 0.2 .XX ± 0.1 .XXX ± 0.05	DRAW 2006/04/14 DATE H. D. LI	PART NO SD - P2 - XX
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